HIGH PERFORMANCE, LOW COST MULTI-CHIP MODULE PACKAGE

ABSTRACT

A high performance, low cost multi-chip module package using a heatsink (41) as a substrate with thin film wiring techniques or multilayered wiring techniques for interconnection of the chips on the surface of the module and a solder column grid array or solder ball grid array (44) for interconnection to the next level of packaging (printed circuit board). The columns or balls create a space between the board and module with the chips (43) being in the space and provide the required interconnect density.

Fig. 4

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